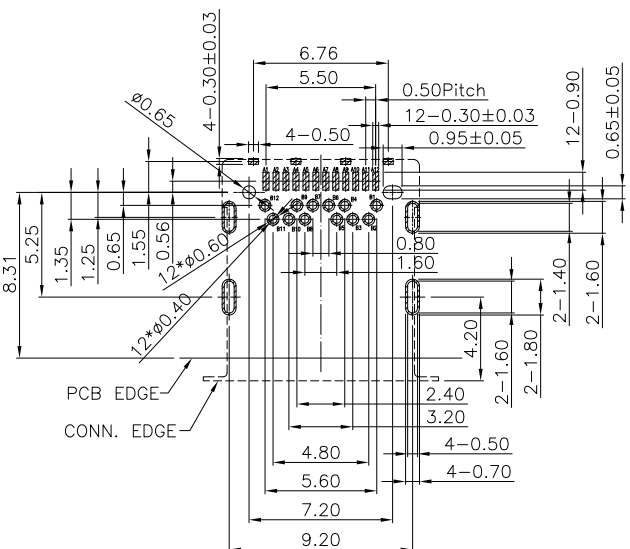
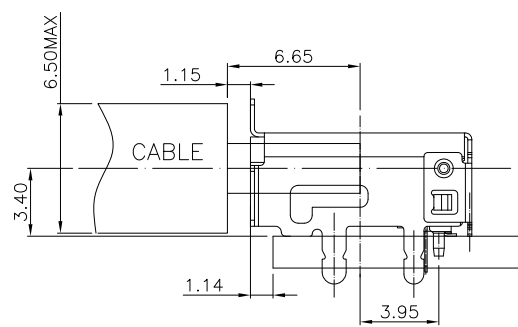
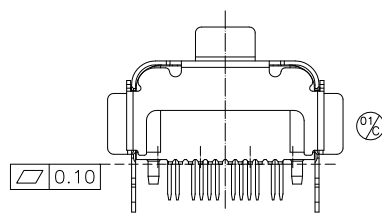
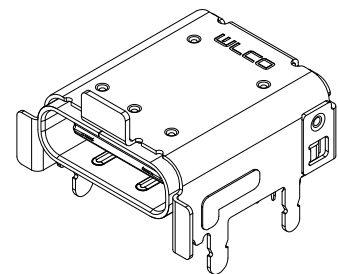


RoHS GP HF

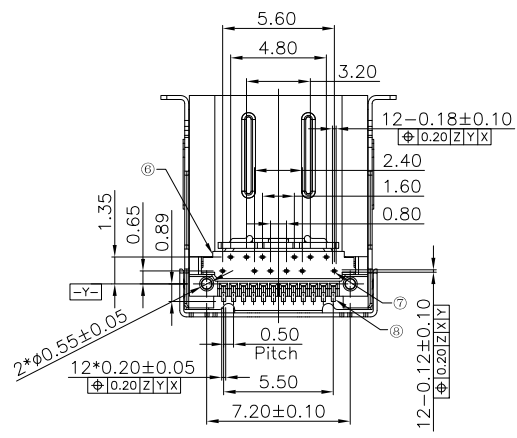
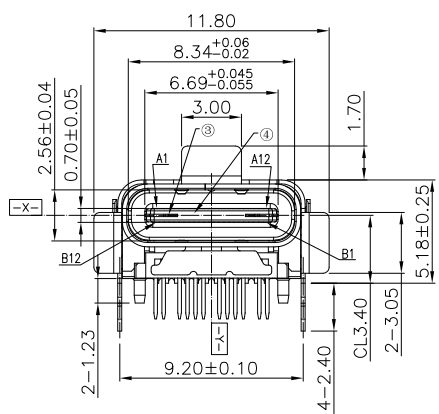
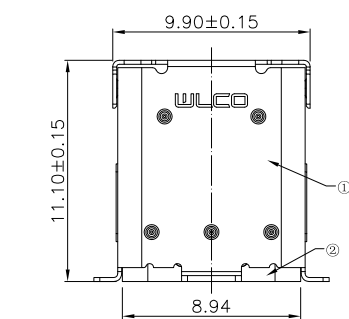
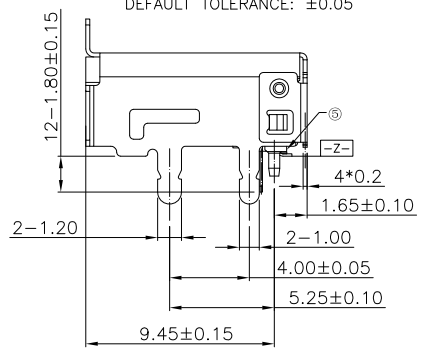
REV.	ECR/N NO.	DESCRIPTION	DRAWN	DATE
A	---	NEW	Rain.Yi	2019/04/18
B	---	Adjust Drawing	XiaoTao.Wu	2020/10/13
C	---	Adjust Drawing	XiaoTao.Wu	2021/09/03

- NOTES:
- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING:VBUS AND GND CONTACTS RATED AT 1.25A, PARALLELED FOR A TOTAL OF 5A;
 - INITIAL CONTACT RESISTANCE:40mΩ Max.;
 - INSULATION RESISTANCE:100MΩ Min.;
 - DIELECTRIC WUTHSTANDING VOLTAGE:100V AC ONE MINUTE.
 - MECHANICAL CHARACTERISTICS:
 - MATING FORCE:5~20N;
 - UNMATING FORCE:8~20N(INITIAL),6~20N(AFTER 10000CYCLES);
 - DURABILITY:200±50 CYCLES/HOUR,10000 CYCLES;
 - OPERATING TEMPERATURE:-55°C~+85°C
 - MEET USB TYPE C STANDARD SPECIFICATION
 - RECOMMENED PROCESS: IR REFLOW 260°C 3~5S



RECOMMENDED PCB LAYOUT(TOP VIEW)

PCB THICKNESS: 1.60±0.05
DEFAULT TOLERANCE: ±0.05

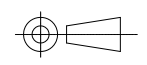


Pin Assignments

Pin	Signal Name	Description	Mating Sequence	Pin	Signal Name	Description	Mating Sequence
A1	GND	Ground return	First	B12	GND	Ground return	First
A2	SSTxp1	Positive half of first SuperSpeed TX differential pair	Second	B11	SSRxp1	Negative half of first SuperSpeed RX differential pair	Second
A3	SSTxn1	Negative half of first SuperSpeed TX differential pair	Second	B10	SSRxn1	Positive half of first SuperSpeed RX differential pair	Second
A4	VBUS	Bus Power	First	B9	VBUS	Bus Power	First
A5	CC1	Configuration Channel	Second	B8	SBU2	Sideband Use	Second
A6	Dp1	Positive half of the USB2.0 differential pair-Position 1	Second	B7	Dn2	Negative half of the USB2.0 differential pair-Position 2	Second
A7	Dn1	Negative half of the USB2.0 differential pair-Position 1	Second	B6	Dp2	Positive half of the USB2.0 differential pair-Position 2	Second
A8	SBU1	Sideband Use	Second	B5	CC2	Configuration Channel	Second
A9	VBUS	Bus Power	First	B4	VBUS	Bus Power	First
A10	SSRxn2	Negative half of second SuperSpeed RX differential pair	Second	B3	SSTxn2	Positive half of second SuperSpeed TX differential pair	Second
A11	SSRxp2	Positive half of second SuperSpeed RX differential pair	Second	B2	SSTxp2	Negative half of second SuperSpeed TX differential pair	Second
A12	GND	Ground return	First	B1	GND	Ground return	First

8	UPPER CONTACT	12	COPPER ALLOY	NICKEL 50μ" MIN. PLATED ON OVERALL AREA GOLD 3μ" PLATED ON THE FUNCTIONAL AREA OF CONTACT. GOLD FLASH PLATED ON SOLDER AREA.
7	LOWER CONTACT	12	COPPER ALLOY	NICKEL 50μ" MIN. PLATED ON OVERALL AREA GOLD 3μ" PLATED ON THE FUNCTIONAL AREA OF CONTACT. GOLD FLASH PLATED ON SOLDER AREA.
6	LOWER IM	1	THERMOPLASTIC UL 94V-0	COLOR: BLACK
5	UPPER IM	1	THERMOPLASTIC UL 94V-0	COLOR: BLACK
4	OVERMOLD	1	THERMOPLASTIC UL 94V-0	COLOR: BLACK
3	SHIELD PLATE	1	STAINLESS STEEL	CLEAN
2	INNER SHELL	1	STAINLESS STEEL	NICKEL PLATING ON OVERALL AREA
1	OUTER SHELL	1	STAINLESS STEEL	NICKEL PLATED ON OVERALL AREA, G/F PLATED ON SOLDER AREA.
NO.	DESCRIPTION	QTY	MATERIAL	SPECIFICATION

TOLERANCE
X.X ±0.35
X.XX ±0.25
X.XXX ±0.10
ANGLE ±1.0°



MODEL NAME: USB TYPE C 3.4H LCP#06; 电子18400接触区 3μ"金, 焊脚区G/F金 中国产SUS301 进口; 台湾SUS304接触, 并在SUS304外壳带翻边到距4.0开槽区刷铜金G/F镀层 HF				DRAWN:	WUXIAOTAO
MODEL NO: WLUS-473E				CHECKED:	WUHUAMING
UNIT:	SCALE:	REVISION:	SHEET	APPROVED:	WUHUAMING
mm	1:1	C	1/1	DATE:	2021/09/03
WULCO 深圳市兴万联电子有限公司 SHENZHEN XING WAN LIAN ELECTRONICS CO., LTD.				DWG NO:	A-WLUS-473E
				FILE:	A